

MC74AC157, MC74ACT157

Quad 2-Input Multiplexer

The MC74AC157/74ACT157 is a high-speed quad 2-input multiplexer. Four bits of data from two sources can be selected using the common Select and Enable inputs. The four outputs present the selected data in the true (non-inverted) form.

The MC74AC157/74ACT157 can also be used as a function generator.

Features

- Outputs Source/Sink 24 mA
- 'ACT157 Has TTL Compatible Inputs
- These are Pb-Free Devices

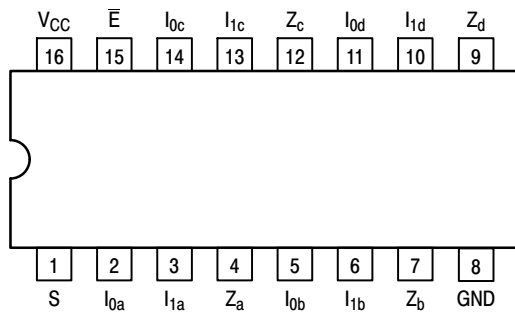


Figure 1. Pinout: 16-Lead Packages Conductors
(Top View)

TRUTH TABLE

Inputs				Outputs
E	S	I ₀	I ₁	Z
H	X	X	X	L
L	H	X	L	L
L	H	X	H	H
L	L	L	X	L
L	L	H	X	H

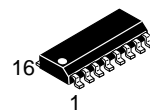
H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial



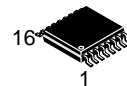
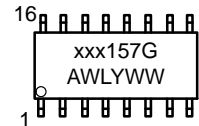
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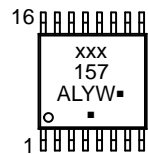
MARKING DIAGRAMS



SOIC-16
D SUFFIX
CASE 751B



TSSOP-16
DT SUFFIX
CASE 948F



xxx = AC or ACT
A = Assembly Location
WL or L = Wafer Lot
Y = Year
WW or W = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

PIN NAMES

PIN	FUNCTION
I _{0a} -I _{0d}	Source 0 Data Inputs
I _{1a} -I _{1d}	Source 1 Data Inputs
E	Enable Input
S	Select Input
Z _a -Z _d	Outputs

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

MC74AC157, MC74ACT157

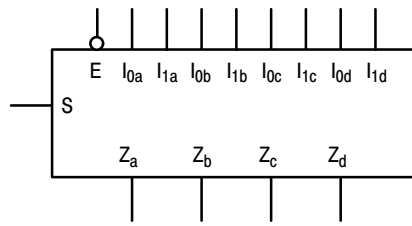


Figure 2. Logic Symbol

FUNCTIONAL DESCRIPTION

The MC74AC157/74ACT157 is a quad 2-input multiplexer. It selects four bits of data from two sources under the control of a common Select input (S). The Enable input (\bar{E}) is active-LOW. When \bar{E} is HIGH, all of the outputs (Z) are forced LOW regardless of all other inputs. The MC74AC157/74ACT157 is the logic implementation of a 4-pole, 2-position switch where the position of the switch is determined by the logic levels supplied to the Select input. The logic equations for the outputs are shown below:

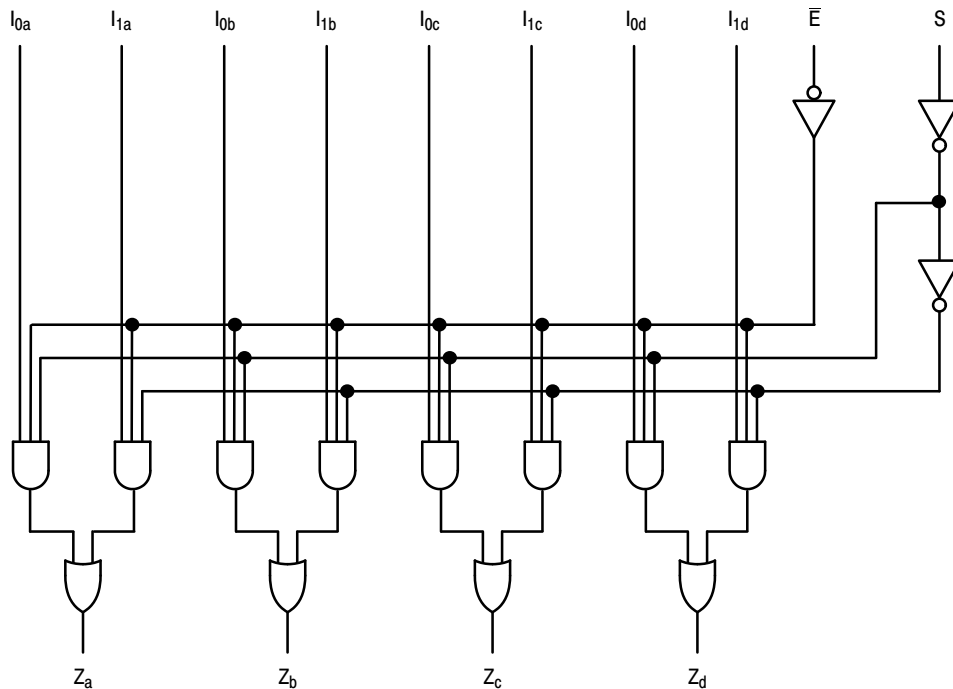
$$Z_a = \bar{E} \cdot (I_{1a} \cdot S + I_{0a} \cdot \bar{S})$$

$$Z_b = \bar{E} \cdot (I_{1b} \cdot S + I_{0b} \cdot \bar{S})$$

$$Z_c = \bar{E} \cdot (I_{1c} \cdot S + I_{0c} \cdot \bar{S})$$

$$Z_d = \bar{E} \cdot (I_{1d} \cdot S + I_{0d} \cdot \bar{S})$$

A common use of the MC74AC157/74ACT157 is the moving of data from two groups of registers to four common output busses. The particular register from which the data comes is determined by the state of the Select input. A less obvious use is as a function generator. The MC74AC157/74ACT157 can generate any four of the sixteen different functions of two variables with one variable common. This is useful for implementing gating functions.



NOTE: This diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 3. Logic Diagram

MC74AC157, MC74ACT157

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	− 0.5 to +7.0	V
V _I	DC Input Voltage	− 0.5 ≤ V _I ≤ V _{CC} + 0.5	V
V _O	DC Output Voltage (Note 1)	− 0.5 ≤ V _O ≤ V _{CC} + 0.5	V
I _{IK}	DC Input Diode Current	± 20	mA
I _{OK}	DC Output Diode Current	± 50	mA
I _O	DC Output Sink/Source Current	± 50	mA
I _{CC}	DC Supply Current per Output Pin	± 50	mA
I _{GND}	DC Ground Current per Output Pin	± 50	mA
T _{STG}	Storage Temperature Range	− 65 to + 150	°C
T _L	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction temperature under Bias	+ 150	°C
θ _{JA}	Thermal Resistance (Note 2) SOIC TSSOP	69.1 103.8	°C/W
P _D	Power Dissipation in Still Air at 65°C (Note 3) SOIC TSSOP	500 500	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 30% – 35%	UL 94 V–0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 4) Machine Model (Note 5) Charged Device Model (Note 6)	> 2000 > 200 > 1000	V
I _{Latch-Up}	Latch-Up Performance Above V _{CC} and Below GND at 85°C (Note 7)	± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.
2. The package thermal impedance is calculated in accordance with JEDEC51–7.
3. 500 mW at 65°C; derate to 300 mW by 10 mW/°C from 65°C to 85°C.
4. Tested to EIA/JESD22–A114–A.
5. Tested to EIA/JESD22–A115–A.
6. Tested to JEDEC22–C101–A.
7. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit
V _{CC}	Supply Voltage	'AC	2.0	5.0	V
		'ACT	4.5	5.0	
V _{IN} , V _{OUT}	DC Input Voltage, Output Voltage (Ref. to GND)	0	–	V _{CC}	V
t _r , t _f	Input Rise and Fall Time (Note 1) 'AC Devices except Schmitt Inputs	V _{CC} @ 3.0 V	–	150	ns/V
		V _{CC} @ 4.5 V	–	40	
		V _{CC} @ 5.5 V	–	25	
t _r , t _f	Input Rise and Fall Time (Note 2) 'ACT Devices except Schmitt Inputs	V _{CC} @ 4.5 V	–	10	ns/V
		V _{CC} @ 5.5 V	–	8.0	
T _J	Junction Temperature (PDIP)	–	–	140	°C
T _A	Operating Ambient Temperature Range	–40	25	85	°C
I _{OH}	Output Current – High	–	–	–24	mA
I _{OL}	Output Current – Low	–	–	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. V_{IN} from 30% to 70% V_{CC}; see individual Data Sheets for devices that differ from the typical input rise and fall times.
2. V_{IN} from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

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DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74AC		74AC	Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C		
			Typ	Guaranteed Limits			
V _{IH}	Minimum High Level Input Voltage	3.0	1.5	2.1	2.1	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
		4.5	2.25	3.15	3.15		
		5.5	2.75	3.85	3.85		
V _{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.9	0.9	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
		4.5	2.25	1.35	1.35		
		5.5	2.75	1.65	1.65		
V _{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I _{OUT} = -50 μA
		4.5	4.49	4.4	4.4		
		5.5	5.49	5.4	5.4		
		3.0	—	2.56	2.46	V	*V _{IN} = V _{IL} or V _{IH} -12 mA I _{OH} -24 mA -24 mA
		4.5	—	3.86	3.76		
		5.5	—	4.86	4.76		
V _{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I _{OUT} = 50 μA
		4.5	0.001	0.1	0.1		
		5.5	0.001	0.1	0.1		
		3.0	—	0.36	0.44	V	*V _{IN} = V _{IL} or V _{IH} 12 mA I _{OL} 24 mA 24 mA
		4.5	—	0.36	0.44		
		5.5	—	0.36	0.44		
I _{IN}	Maximum Input Leakage Current	5.5	—	±0.1	±1.0	μA	V _I = V _{CC} , GND
I _{OLD}	†Minimum Dynamic Output Current	5.5	—	—	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}		5.5	—	—	-75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	—	8.0	80	μA	V _{IN} = V _{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

NOTE: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V _{CC} * (V)	74AC			74AC		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay S to Z _n	3.3 5.0	1.5 1.5	7.0 5.5	11.5 9.0	1.5 1.5	13.0 10.0	ns	3-6
t _{PHL}	Propagation Delay S to Z _n	3.3 5.0	1.5 1.5	6.5 5.0	11.0 8.5	1.5 1.0	12.0 9.5	ns	3-6
t _{PLH}	Propagation Delay E to Z _n	3.3 5.0	1.5 1.5	7.0 5.5	11.5 9.0	1.5 1.5	13.0 10.0	ns	3-6
t _{PHL}	Propagation Delay E _n to Z _n	3.3 5.0	1.5 1.5	6.5 5.5	11.0 9.0	1.5 1.0	12 9.5	ns	3-6
t _{PLH}	Propagation Delay I _n to Z _n	3.3 5.0	1.5 1.5	5.0 4.0	8.5 6.5	1.0 1.0	9.0 7.0	ns	3-5
t _{PHL}	Propagation Delay I _n to Z _n	3.3 5.0	1.5 1.5	5.0 4.0	8.0 6.5	1.0 1.0	9.0 7.0	ns	3-5

*Voltage Range 3.3 V is 3.3 V ±0.3 V.

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

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DC CHARACTERISTICS

Symbol	Parameter	V _{CC} (V)	74ACT		74ACT	Unit	Conditions
			T _A = +25°C		T _A = -40°C to +85°C		
			Typ	Guaranteed Limits			
V _{IH}	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{IL}	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V _{OUT} = 0.1 V or V _{CC} - 0.1 V
V _{OH}	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I _{OUT} = -50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	*V _{IN} = V _{IL} or V _{IH} -24 mA I _{OH} -24 mA
V _{OL}	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I _{OUT} = 50 μA
		4.5 5.5	- -	0.36 0.36	0.44 0.44	V	*V _{IN} = V _{IL} or V _{IH} 24 mA I _{OL} 24 mA
I _{IN}	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μA	V _I = V _{CC} , GND
ΔI _{CCT}	Additional Max. I _{CC} /Input	5.5	0.6	-	1.5	mA	V _I = V _{CC} - 2.1 V
I _{OLD}	†Minimum Dynamic Output Current	5.5	-	-	75	mA	V _{OLD} = 1.65 V Max
I _{OHD}		5.5	-	-	-75	mA	V _{OHD} = 3.85 V Min
I _{CC}	Maximum Quiescent Supply Current	5.5	-	8.0	80	μA	V _{IN} = V _{CC} or GND

*All outputs loaded; thresholds on input associated with output under test.

†Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS (For Figures and Waveforms – See Section 3 of the ON Semiconductor FACT Data Book, DL138/D)

Symbol	Parameter	V _{CC} * (V)	74ACT			74ACT		Unit	Fig. No.
			T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF			
			Min	Typ	Max	Min	Max		
t _{PLH}	Propagation Delay S to Z _n	5.0	2.0	–	9.0	1.5	10.0	ns	3–6
t _{PHL}	Propagation Delay S to Z _n	5.0	2.0	–	9.5	2.0	10.5	ns	3–6
t _{PLH}	Propagation Delay E _n to Z _n	5.0	1.5	–	10	1.5	11.5	ns	3–6
t _{PHL}	Propagation Delay E _n to Z _n	5.0	1.5	–	8.5	1.0	9.0	ns	3–6
t _{PLH}	Propagation Delay I _n to Z _n	5.0	1.5	–	7.0	1.0	8.5	ns	3–5
t _{PHL}	Propagation Delay I _n to Z _n	5.0	1.5	–	7.5	1.0	8.5	ns	3–5

*Voltage Range 5.0 V is 5.0 V ±0.5 V.

CAPACITANCE

Symbol	Parameter	Value – Typ	Unit	Test Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = 5.0 V
C _{PD}	Power Dissipation Capacitance	50	pF	V _{CC} = 5.0 V

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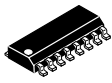
ORDERING INFORMATION

Device Order Number	Package	Shipping†
MC74AC157DG	SOIC–16 (Pb–Free)	48 Units / Rail
MC74AC157DR2G	SOIC–16 (Pb–Free)	2500 Tape & Reel
MC74AC157DTR2G	TSSOP–16 (Pb–Free)	2500 Tape & Reel
MC74ACT157DG	SOIC–16 (Pb–Free)	48 Units / Rail
MC74ACT157DR2G	SOIC–16 (Pb–Free)	2500 Tape & Reel
MC74ACT157DTR2G	TSSOP–16 (Pb–Free)	2500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



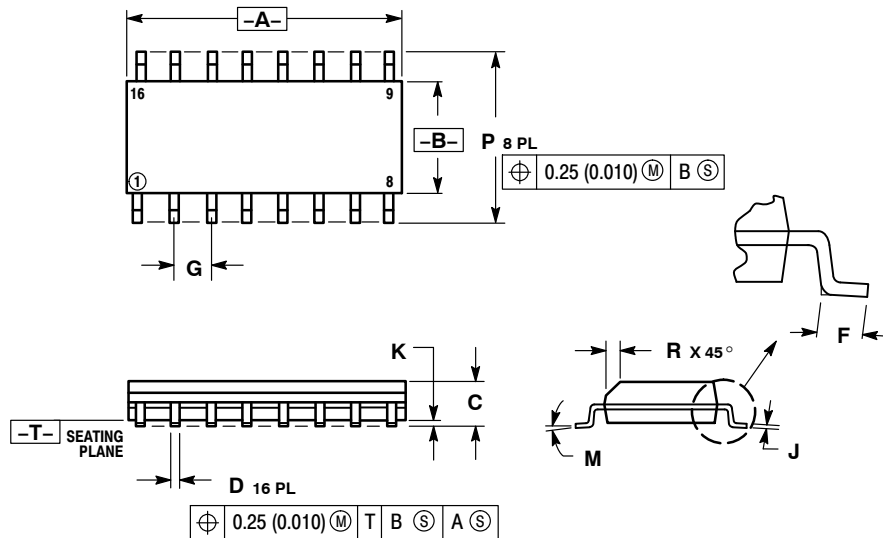
SCALE 1:1

SOIC-16

CASE 751B-05

ISSUE K

DATE 29 DEC 2006



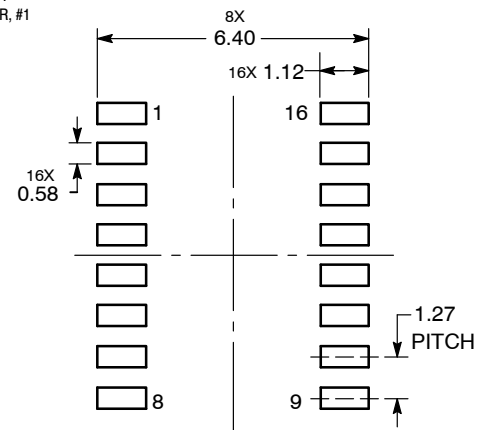
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1: PIN 1. COLLECTOR 2. BASE 3. EMITTER 4. NO CONNECTION 5. EMITTER 6. BASE 7. COLLECTOR 8. COLLECTOR 9. BASE 10. EMITTER 11. NO CONNECTION 12. EMITTER 13. BASE 14. COLLECTOR 15. EMITTER 16. COLLECTOR	STYLE 2: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION 4. CATHODE 5. CATHODE 6. NO CONNECTION 7. ANODE 8. CATHODE 9. CATHODE 10. ANODE 11. NO CONNECTION 12. CATHODE 13. CATHODE 14. NO CONNECTION 15. ANODE 16. CATHODE	STYLE 3: PIN 1. COLLECTOR, DYE #1 2. BASE, #1 3. EMITTER, #1 4. COLLECTOR, #1 5. COLLECTOR, #2 6. BASE, #2 7. EMITTER, #2 8. COLLECTOR, #2 9. COLLECTOR, #3 10. BASE, #3 11. EMITTER, #3 12. COLLECTOR, #3 13. COLLECTOR, #4 14. BASE, #4 15. EMITTER, #4 16. COLLECTOR, #4	STYLE 4: PIN 1. COLLECTOR, DYE #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. COLLECTOR, #3 6. COLLECTOR, #3 7. COLLECTOR, #4 8. COLLECTOR, #4 9. BASE, #4 10. EMITTER, #4 11. BASE, #3 12. EMITTER, #3 13. BASE, #2 14. EMITTER, #2 15. BASE, #1 16. EMITTER, #1
STYLE 5: PIN 1. DRAIN, DYE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. DRAIN, #3 6. DRAIN, #3 7. DRAIN, #4 8. DRAIN, #4 9. GATE, #4 10. SOURCE, #4 11. GATE, #3 12. SOURCE, #3 13. GATE, #2 14. SOURCE, #2 15. GATE, #1 16. SOURCE, #1	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. CATHODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE 15. ANODE 16. ANODE	STYLE 7: PIN 1. SOURCE N-CH 2. COMMON DRAIN (OUTPUT) 3. COMMON DRAIN (OUTPUT) 4. GATE P-CH 5. COMMON DRAIN (OUTPUT) 6. COMMON DRAIN (OUTPUT) 7. COMMON DRAIN (OUTPUT) 8. SOURCE P-CH 9. SOURCE P-CH 10. COMMON DRAIN (OUTPUT) 11. COMMON DRAIN (OUTPUT) 12. COMMON DRAIN (OUTPUT) 13. GATE N-CH 14. COMMON DRAIN (OUTPUT) 15. COMMON DRAIN (OUTPUT) 16. SOURCE N-CH	

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SOIC-16	PAGE 1 OF 1

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MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



TSSOP-16 WB
CASE 948F
ISSUE B

DATE 19 OCT 2006



NOTES:

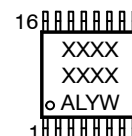
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

RECOMMENDED SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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